P 685

ELAST UNIVERSAL

Elastic adhesive for bonding solid and engineered wood flooring

CERESIT
P685_TM_11_0816

CHARACTERISTICS

- ▶ **Suitable for plenty types of wood flooring**
- ▶ **Long-lasting strong bond**
- ▶ **No priming required for most substrates**
- ▶ **With Flextec™ Technologie:**
  - **– Water- and solvent-free**
  - **– Excellent workability**
  - **– Easier removal of stains**
  - **– Durable elastic**

SCOPE OF USE

Ceresit P 685 is a very low-emission, single-component special adhesive for bonding:
– strip wood flooring
– mosaic, on-edge lamella and lamparquet
– engineered wood flooring
– solid floorboards, greater than 16 mm thickness and lower than 160 mm width

Ceresit P 685 can be used on:
– mineral screeds
– dry screed constructions, chipboards (V100) and OSB boards
– Ceresit levelling compounds DX, XXL-XPRESS, AS1
– natural stones, tiles and terrazzo.

The elastic bond absorbs shear forces and thus permanently reduces the influence of tensile stresses on the substrate. Flextec® is a userfriendly alternative to conventional PUR adhesives.
Use Ceresit P 625 for bonding solid wood flooring of larger formats, exotic woods and wood block.
Ceresit P 685 meets the highest requirements for indoor air quality and environemental compatibility.

SUBSTRATE PREPARATION

The substrates must comply with the requirements of ATV DIN 18 356 “Wood flooring works”, BS CP 8201 & 8204 or comparable national standards. In particular, they must be clean, free from structural defects, firm, dry and free of substances which may impair adhesion. New substrates must be thoroughly ground and vacuumed to free them of dust and adhesioninhibiting layers. Nonabsorbent, smooth substrates, e. g. ceramic tile or terrazzo floors, must be cleaned and sanded down and vacuumed if necessary. The wood flooring is bonded on top of those prepared substrates without need for a priming coat. After the necessary mechanical preparation prime old substrates and mastic asphalt screeds in any case with Ceresit R 755 or Ceresit R 740. Uneven as well as old substrates must be levelled off with the recommended Ceresit levelling compounds with at least 2 mm thickness.

APPLICATION

Stir the adhesive well and apply it evenly to the substrate with a suitable notched trowel. Only apply as much adhesive as can be laid with wood flooring within the working time. Ensure the backing of the wood flooring is well wetted. Avoid gluing the edges. Allow a minimum gap of 10 mm from walls. Remove the spacer wedges from the perimeter joints immediately after installation. Avoid walking on the parquet surface both during and for at least 24 hours after installation.

IMPORTANT INFORMATION

- Best possible indoor air quality after floor installation work requires conformity to the standard working conditions as well as completely dry substrates, primers and leveling compounds.
- Especially multi-layer wood flooring with MDF/HDF middle layer and solid wood flooring without tongue and -groove joint have a higher tendency to "buckle" with seasonal fluctuations in humidity (e. g. summer/winter change). Elastic adhesives cannot completely prevent such effects. In the above cases, we recommend using Ceresit P 625 to ensure shear-resistant bonding.
- Do not use Ceresit P 685 in direct contact with Ceresit R 777 or Ceresit R 766 waterbased primers.
- Remove any skin that may have formed on the product (e.g. caused by improper storage), do not stir it in.
- Prevent the adhesive from penetrating into the wood flooring joints since interaction with any subsequently applied sealing finishes cannot be excluded.
- Carry out floor installation work at floor temperatures above 15 °C, air temperature above 18 °C and the relative humidity below 75 %.
- Immediately remove fresh spots of adhesive with industrial spirit (alcohol).
- Clean the tools also with industrial spirit (alcohol) immediately after use.
- Tightly close opened buckets and use them up as soon as possible.
- The curing time may vary depending on temperature and relative humidity. They will be shorter at higher temperatures and higher humidity, but longer at lower temperatures and lower humidity.

PRODUCT SAFETY

Ceresit P 685 is solvent-free and therefore a suitable alternative to solvent-containing products. Methanol is released during the curing process. Therefore ensure adequate ventilation during the application and drying process. The risk of medium- or long-term release of appreciable concentrations of volatile organic compounds (VOCs) into the ambient air is negligible.
Eating, drinking and smoking should be avoided while working with this product. Wear protective gloves and protective clothing during work.
In case of contact with the eyes or the skin, rinse immediately with plenty of water. In case of contact with the eyes, also consult a doctor.
Information for allergy sufferers on: +49 (0)211 797-0.
Keep out of reach of children.
For professional users.
Safety data sheet available on www.ceresit.com.

GISCODE RS 10	silane-modified polymers, contains methoxy silane
EMICODE EC 1 PLUS R	very low-emission according to GEV

TECHNICAL INFORMATION

Please also follow the instructions in the following information sheets:

1. The norm guidelines and regulations of the appropriate national organizations and professional associations.
2. Floor covering manufacturers' product installation instructions.
3. Information sheets issued by the Technische Kommission Bauklebstoffe (www.klebstoffe.com, see under "Publikationen").
4. Generally recognized rules of flooring technology as well as the applicable national standards.

DISPOSAL

Do not allow product to reach sewage system or any water course. Do not allow to penetrate the ground/soil. Only recycle totally empty packages. Dispose of hardened product residues as industrial waste similar to household waste or in the container for commercial/construction site waste. Dispose of unhardened product residues as hazardous waste.
European waste code number (EWC): 08 04 10

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TECHNICAL DATA

Supplied as	beige paste
Packaging	plastic bucket, 16 kg
Shipping unit	32 buckets per pallet
Open time	none
Working time	approx. 30 minutes
Load bearing	after approx. 24 hours, on non-absorbent substrates after 48 hours
Sanding work/ surface treatment	after 24 hours at the earliest, on non-absorbent substrates after 48 hours
Temperature resistance after curing for transport for storage	 up to +50 °C, can be used on underfloor heating constructions –20 °C to +50 °C +10 °C to +30 °C
Impact sound reduction	13 dB acc. to DIN EN 140-8
Room sound reduction	12 dB
Shelf life	12 months, cool and dry

The above times were measured under standard climatic conditions (23 °C/50 % rel. air humidity). Please note that under other climatic conditions curing resp. hardening may be accelerated or delayed.

CONSUMPTION

wood flooring, on-edge lamella (or industrial wood flooring), lamparquet		
notch size B 3	approx. 850 g/m²	coverage/bucket: 19 m²
strip wood flooring, multilayer/prefinished wood flooring up to 1200 mm length		
notch size B 11	approx. 1050 g/m²	coverage/bucket: 15 m²
larger formats, e.g. floorboards made of solid wood or prefinished wood flooring		
notch size B 15	approx. 1150 g/m²	coverage/bucket: 14 m²
Ceresit TF 302, TF 303/305		
notch size B 2	approx. 750 g/m²	coverage/bucket: 22 m²

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